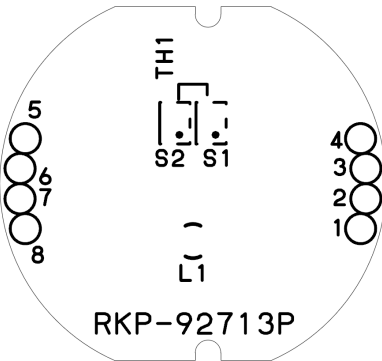
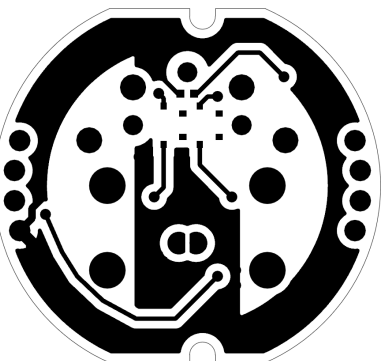


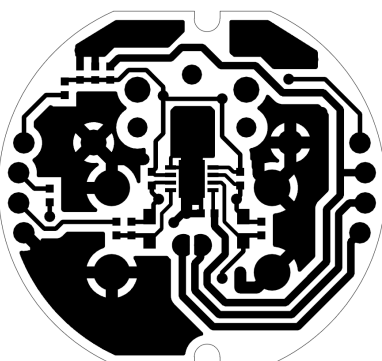
RKP-92713



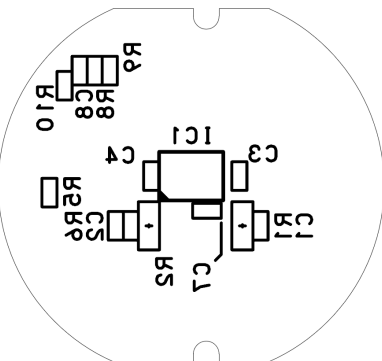
SILK PRINT FOR  
PARTS SIDE



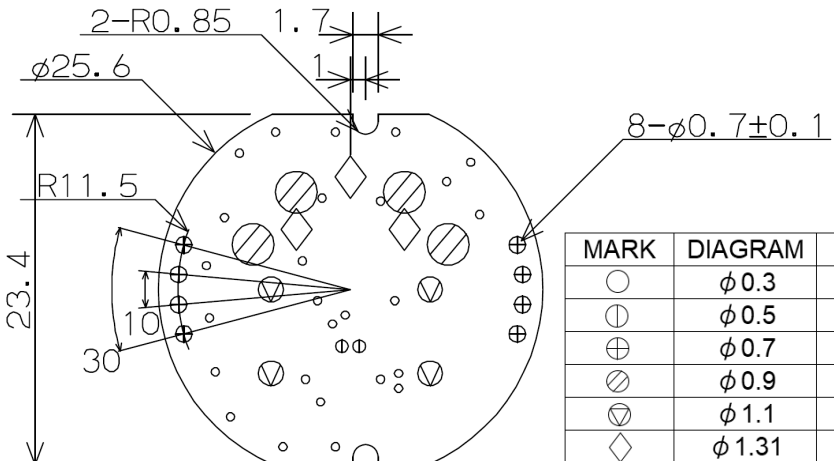
PARTS SIDE



SOLDERING SIDE



SILK PRINT FOR  
SOLDERING SIDE



MARK	DIAGRAM	HOLE	MEMO
○	φ0.3	TH	
⊙	φ0.5	TH	
⊕	φ0.7	TH	
⊗	φ0.9	TH	
⊖	φ1.1	TH	
◇	φ1.31	NTH	

THROUGH HOLE

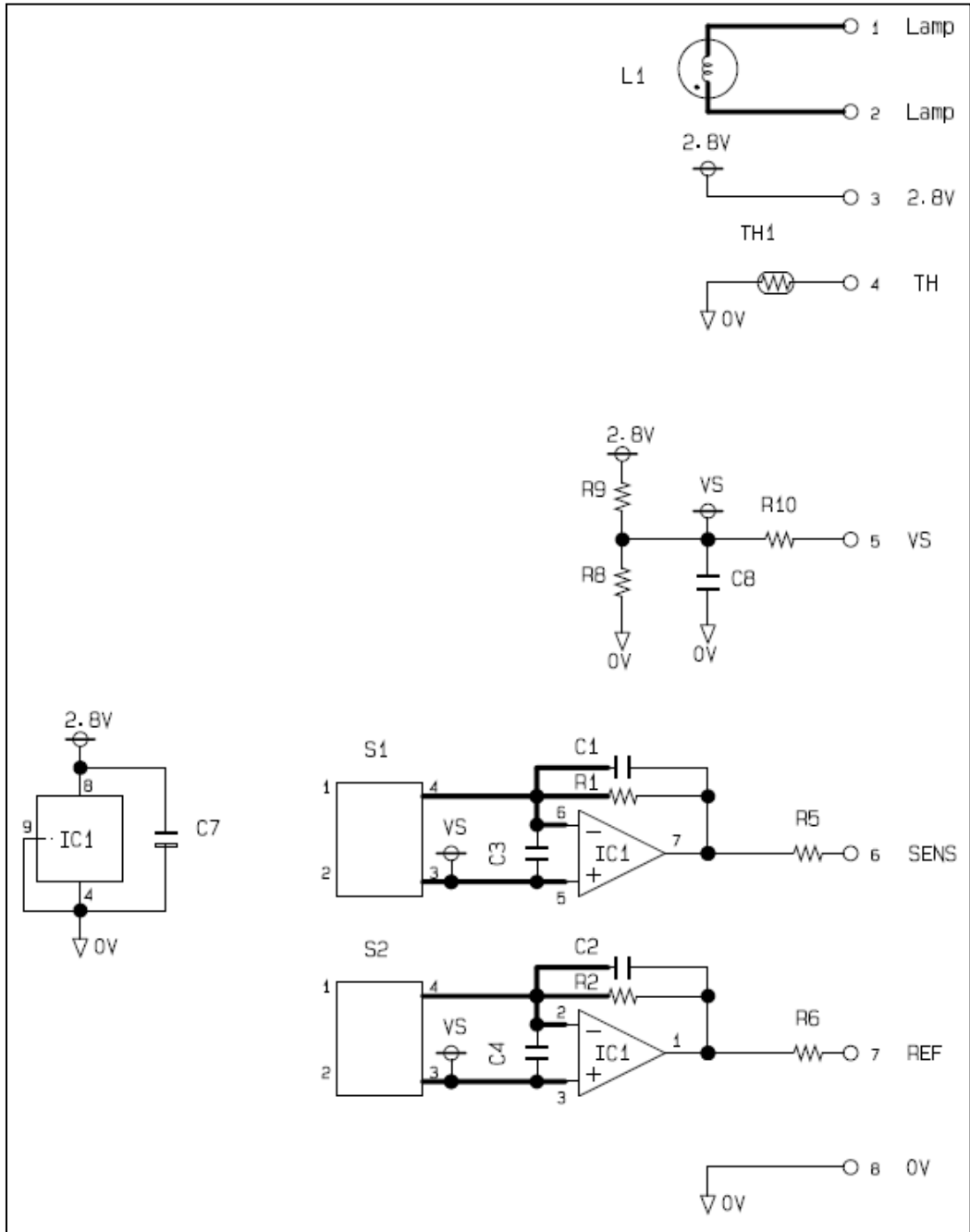
All drawings are view of parts side  
SCALE 2:1

**SPECIFICATION FOR PCB**  
・PCB No. : RKP-92713P  
・Material : Glass epoxy  
・Thickness : 1.0mm  
・Layer number : 2  
・Thickness copper film : 18um  
・Minimum conductor width : 0.25mm  
・CTI : 100 above

PARTS LIST

Mark of drawing	Kind of parts	Rating / Model of parts	Remarks
IC1	IC(OPAMP)	LTC2055HDD[AD]	
L1	T-1 Short IBP Lamp	OL-7152IBP/A [OSHINO] Refer to E4-6991-5769-40-01K, NL/DEK/ExTR 12.0033	
TH1	Chip thermistor	Rt25 = 4.7k ohm -470 k ohm / 5%, B=3000K-5000K (1005)	
S1,S2	IR Sensor	IR1011 [ASAHI KASEI]	
R1,R2	Chip fixed resistor or Chip jumper	10 ohm - 10M ohm / 1% 0.1W 50m ohm max 1A (1608)	
R5,R6,R8,R9,R10	Chip fixed resistor or Chip jumper	30 ohm - 10M ohm / 1%, 0.063W or 50m ohm max 1A (1005)	
C1,C2,C3,C4,C7,C8	Chip multilayer capacitor	Total capacitance 1.1uFmax	

All components may be replaced with equivalent components or may not be mounted.



SCHEMATIC

注 記 NOTES		改版担当者 REV. BY	改版日 REVISED	名 称 NAME
改版回数 REV. 1		小野圭	2021.6.10	SENSOR PCB
承認 APPROVED		製 図 DRAWN	作成日 DATE	図 番 DWG. NO.
北村正英		神沢朋和	2021.4.7	E 3 - 6 9 9 1 - 6 1 9 7 - 2 0 - 0 1 K
総頁数 PAGES 1		検 討 CHECKED		
小野圭		理研計器株式会社		
		機密情報 / CONFIDENTIAL		